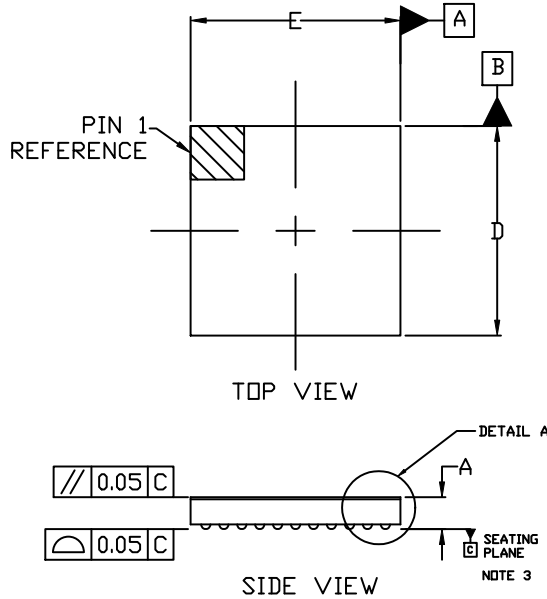


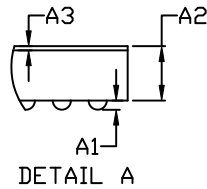
WLCSP120, 4.086x4.086x0.62
CASE 567WG
ISSUE O

DATE 16 APR 2018

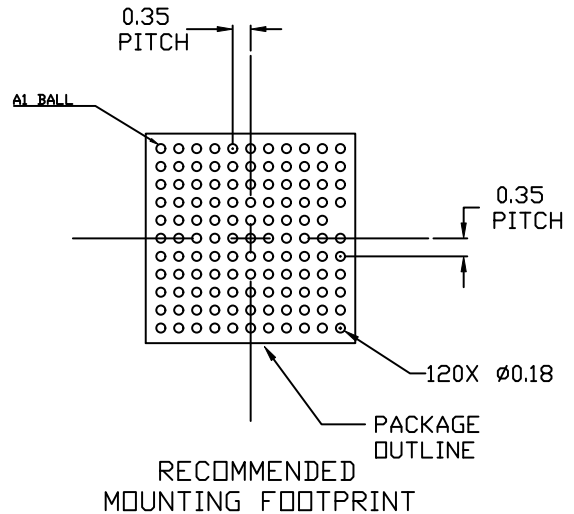
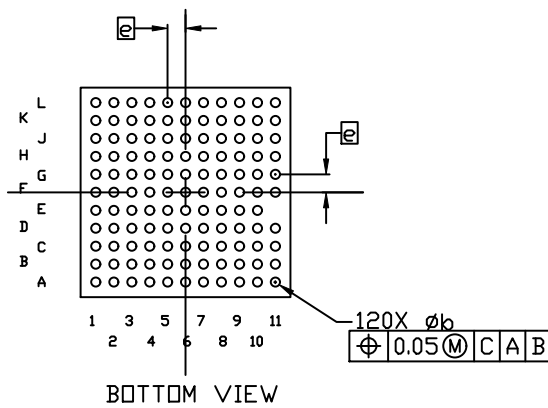


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. SEATING PLANE IS AT THE SPHERICAL CROWN SOLDER BALLS.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.58	0.62	0.66
A1	0.07	0.09	0.11
A2	0.51	0.53	0.55
A3	0.04 REF		
b	0.145	0.175	0.205
D	4.056	4.086	4.116
E	4.056	4.086	4.116
e	0.35 BSC		




GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
 A = Assembly Location
 WL = Wafer Lot
 YY = Year
 WW = Work Week
 ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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